

Application Serial No. 10/750,580
Response dated November 23, 2005
Reply to Restriction Requirement dated November 4, 2005

Amendments to Claims

This listing of claims will replace all prior versions and listing of claims in the application:

Listing of Claims

1. (original) An integrated package comprising:
 - a first wafer having a first surface;
 - a second wafer having a first surface bonded at a first perimeter to the first surface of the first wafer; and
 - a recess formed in the first surface of the first wafer in a second perimeter situated within the first perimeter.
2. (original) The package of claim 1, further comprising a first bump pattern in the first surface of the first wafer within the second perimeter.
3. (original) The package of claim 2, further comprising a second bump pattern on a second surface of the first wafer.
4. (original) The package of claim 3, further comprising a seal between the first and second wafers at the first

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perimeter.

5. (original) The package of claim 4, wherein the seal comprises:
- a spacer material; and
 - a layer of malleable material.
6. (original) The package of claim 5, wherein the seal further comprises a layer of bondable material.
7. (original) The package of claim 6, further comprising structural supports in the recess of the first wafer.
8. (original) The package of claim 7, further comprising at least one pumpout opening in the first wafer.
9. (original) The package of claim 8, wherein the first and second wafers comprise silicon.
- 10-30. (canceled)